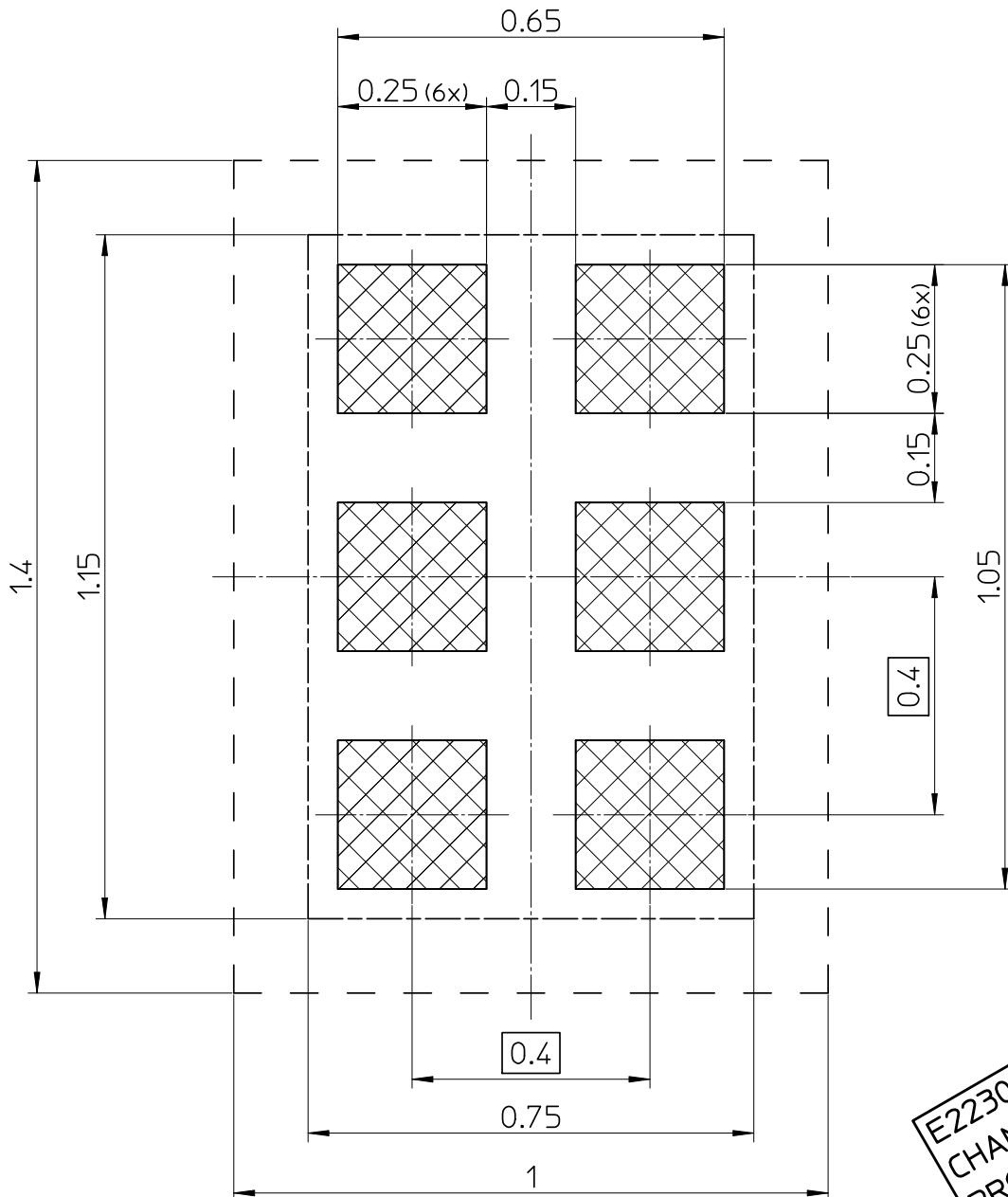




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REFLOW SOLDERING

E2230  
CHANGE  
PROPOSAL  
2013-03-14

- Occupied Area
- Solder Lands
- Solder Resist
- Solder Paste

|                          |                 |                  |                               |                      |               |               |
|--------------------------|-----------------|------------------|-------------------------------|----------------------|---------------|---------------|
| Proj.<br>                | Scale<br>100:1  | Unit<br>mm       | Tol.unless otherw.stated<br>± | ISO 1302<br>Ra in um | ISO 1101<br>A | Typ u a.      |
| SOLDER LAYOUT<br>SOT1232 |                 |                  | 4340 711 00150                |                      |               |               |
| Name: SHI Yuning         | DWG No.: EH2381 | 1                | 110                           | -                    | 1             | 010 - - - A 4 |
| PV                       | Check :         | Dat.: 2013-03-14 | (c) NXP Semiconductors / TCC  |                      |               |               |